PRESS RELEASE
February 2026

IMAPS Announces Purchase of the 3D InCites Platform

The technical and media platform for microelectronics and advanced packaging is now a part of the IMAPS portfolio.

The International Microelectronics Assembly and Packaging Society (IMAPS) is pleased to announce a major milestone for the Society, with IMAPS taking over the "stewardship" of the trusted 3D InCites platform which was owned by Françoise von Trapp and her partner Martijn Pierik. Following Françoise's retirement, IMAPS purchased the 3D InCites platform, including its website, content library, and podcasts. These longstanding industry resources are now part of the IMAPS portfolio. IMAPS leadership aims to continue 3D InCites' legacy going forward as an important technical and media platform for the advanced packaging industry.

Françoise von Trapp expressed excitement about the transition, stating that "by passing the torch to IMAPS, I feel confident that they will preserve our legacy far into the future. It is a natural fit, and I'm excited to see where IMAPS takes 3D InCites next."

Brian Schieman, IMAPS Executive Director, spoke similarly by stating that "following the many years of close collaborations between our organizations, our executive leadership team recognized that IMAPS was in a unique position to offer a seamless transition of this platform, with a vision and strategy for future expansion of these invaluable industry resources."

3D InCites has been a media supporter of IMAPS for more than a decade and the Official Industry Partner of IMAPS for the past five years. Other notable collaborations included IMAPS hosting the 3D InCites Awards, 3D InCites podcasting from IMAPS signature conferences, and the Back Yard Olympics fundraiser to support the 3D InCites Scholarship through the IMAPS Microelectronics Foundation.

Following von Trapp's retirement and the closure of 3D InCites, LLC, the 3D InCites platform will continue under the IMAPS umbrella, delivering a technology and innovation spotlight for engineers, researchers, manufacturers, and students across the microelectronics and advanced packaging sectors. IMAPS plans for future content and media under the 3D InCites platform covering a variety of leading technologies, including device and chiplet packaging, advanced thermal solutions, packaging for AI/HPC, 3D integration, heterogeneous integration, photonics/CPO, and next generation materials, to name a few. Further details will be shared soon.

"I think I speak for all our IMAPS members and volunteers, as well as the broader industry, when I say thank you to Françoise for all that she has done for the industry over the past 17 years – she will be greatly missed. We look forward to writing this next chapter for the platform she created," said Schieman.

IMAPS looks to share full details on the future activities planned for 3D InCites media platform at the IMAPS 22nd International Conference and Exhibition on Device Packaging in Phoenix, March 2-5 – a fitting event given the significance of this Conference throughout the relationship between IMAPS and 3D InCites over the past 16 years!

Visit the 3D InCites website

About IMAPS

The International Microelectronics Assembly and Packaging Society is the largest society dedicated to the advancement and growth of microelectronics and electronics packaging. Worldwide, IMAPS offers educational and marketing opportunities for industry professionals, organizations, and students through technical conferences and workshops, professional development courses, a microelectronics packaging research library, local chapters and exhibitions. The Society encompasses a wide-range of technologies critical to microelectronics assembly and packaging: on-shoring, heterogenous integration, FOWLP, 2.5D/3D, system-in-package, photonics/optical, power packaging, CPI, package design/modeling, interconnects, wire bonding, flip chip, MEMS, sensors, packaging for 5g/6g, RF/wireless, signal/power integrity, advanced materials, substrates and more.

. . .

Media contact:	bschieman@imaps.org
Brian Schieman, IMAPS	(919) 293-5000